

Number of contacts 6, 10, 14, 16, 20, 26, 34, 40, 50, 60, 64

Contact arrangement straight

Contact length 5.5 mm

Approvals IEC 60603-13
DIN EN 60603-13
D 2632
BT 224
NFC 93-428 (HE 10)
UL recognized: E102079



Pitch 2.54 mm [0.100"]

Working current 1 A

Test voltage $U_{r.m.s.}$ 1 kV

Contact resistance $\leq 20 \text{ m}\Omega$
Insulation resistance $\geq 10^9 \Omega$

Temperature range -55 °C ... + 105 °C
The maximum temperature includes heating of contacts and ambient temperature

Press-in

Diameter of pcb plated through holes $\varnothing 1.0^{+0.09}_{-0.06} \text{ mm}$

Recommended pcb holes for press-in process
Hole: $\varnothing 1.12 - 1.15 \text{ mm}$
Cu : 25 – 75 μm
Sn : 5 – 15 μm

Pcb thickness 1.6 – 3.2 mm

Materials

Moulding Thermoplastic resin (PBT)
UL 94-V0

Contact surface

Contact zone plated according to performance level¹⁾

Insertion and withdrawal forces

Number of contacts	Maximum force [N]	
	Performance level 1 and 2	Performance level 3
6	12	18
10	20	30
14	28	42
16	32	48
20	40	60
26	52	78
34	68	102
40	80	120
50	100	150
60	120	180
64	128	192

¹⁾ Performance level 3 as per IEC 60603-13, ≥ 50 mating cycles, no gas test
Performance level 2 as per IEC 60603-13, ≥ 250 mating cycles, 4 days gas test
S4, plating = 0.76 μm (30 μinch) Au or PdNi equivalent